

Customer No.: 31561  
Application No.: 10/605,214  
Docket No.: 9789-US-PA

**AMENDMENT**

Please amend the claims in the application according to the following listing of claims.

1. (previously presented) A method of fabricating an organic light emitting diode device, comprising:

(a) providing a substrate having an organic light emitting diode unit thereon;

(b) forming a passivation layer on the substrate to cover the organic light emitting diode unit; ~~and~~

(c) providing an ion beam to perform surface treatment on the passivation layer, wherein the ion beam is provided by ion implantation;

(d) forming a plastic layer on the passivation layer.

2. (original) The method according to Claim 1, wherein the passivation layer is formed of either silicon nitride or silicon oxide.

Claims 3-4 (cancelled)

Claim 5 (cancelled)

6. (original) The method according to Claim 5, further comprising repeating the steps (b) to (d) at least once.

7. (original) The method according to Claim 5, wherein the plastic layer is made of ultra high molecular weight polyethylene or PMMA.

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8. (currently amended) A method of forming a solid passivation layer to protect an electronic device formed on a substrate, comprising:

- (a) forming a passivation layer to cover the electronic device; ~~and~~
- (b) providing an ion beam to perform surface treatment on the passivation layer, wherein the ion beam is provided by ion implantation; and
- (c) forming a plastic layer on the passivation layer; and
- (d) repeating steps (a) to (c) at least once.

9. (original) The method according to Claim 8, wherein the passivation layer is made of silicon nitride or silicon oxide.

Claims 10-12 (cancelled)

Claim 13. (cancelled)

14. (previously presented) The method according to Claim 8, wherein the plastic layer is made of ultra high molecular polyethylene or PMMA.